



Politecnico
di Torino

Validation of the 65 nm TPSCo CMOS imaging technology for the ALICE ITS3

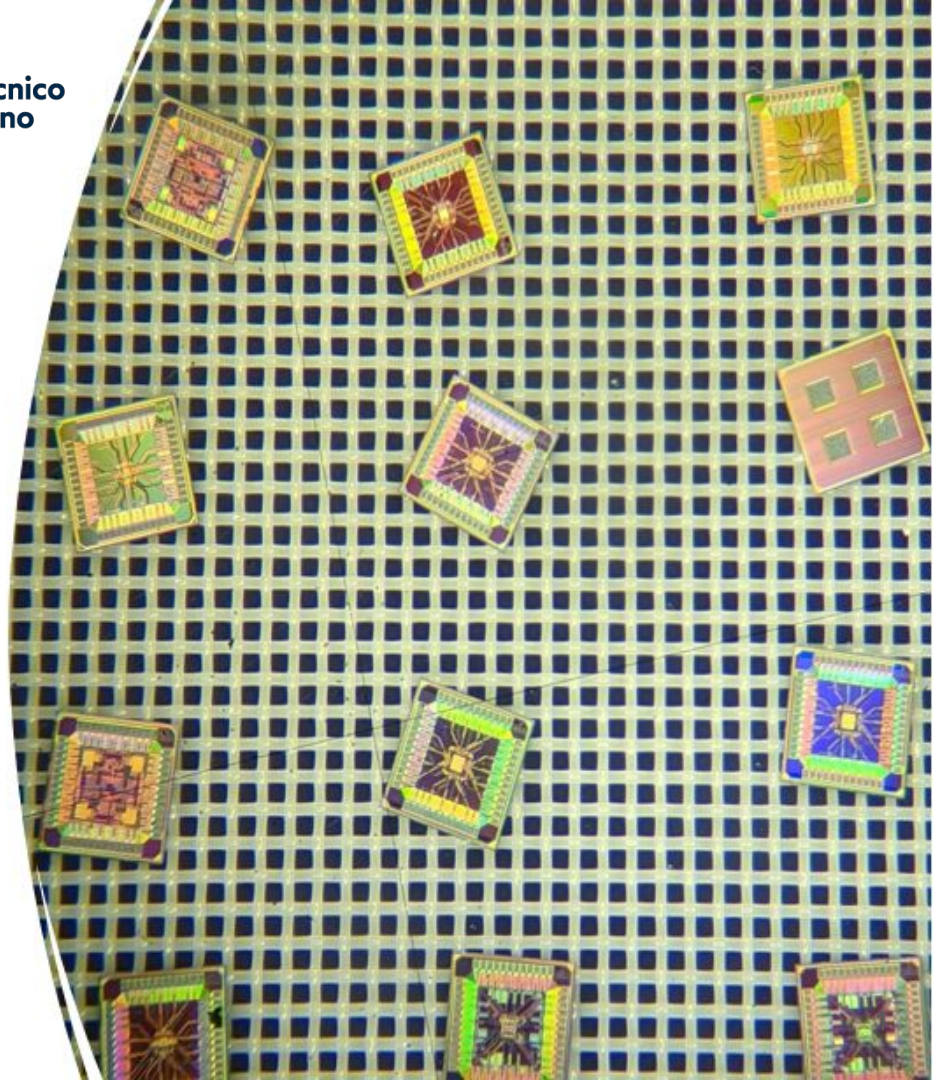
Chiara Ferrero*

on behalf of the ALICE collaboration

*Politecnico Torino, INFN Torino

TWEPP 2023

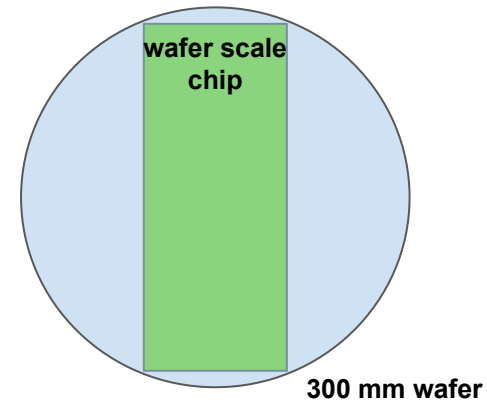
Oct 2 – 6, 2023



65 nm CMOS IS technology

STANDARD

- Available on 300 mm wafers
- Provides 2D stitching
- Chips thinned down to $\leq 50 \mu\text{m}$
- 7 metal layers



3 different implant geometries:

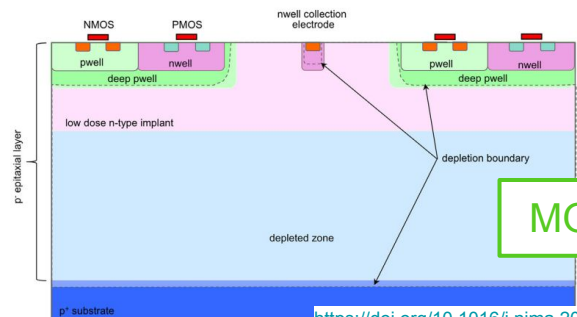
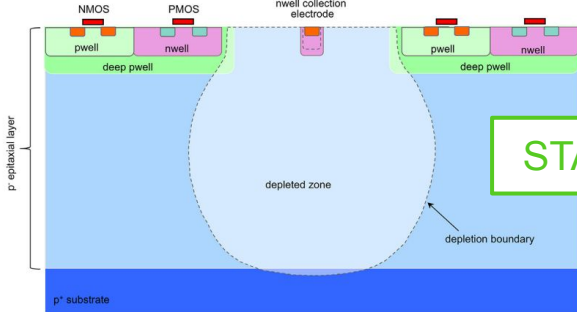
- standard
- modified (B)
- modified with gap (P)

4 different pixel pitches (10, 15, 20, 25 μm)

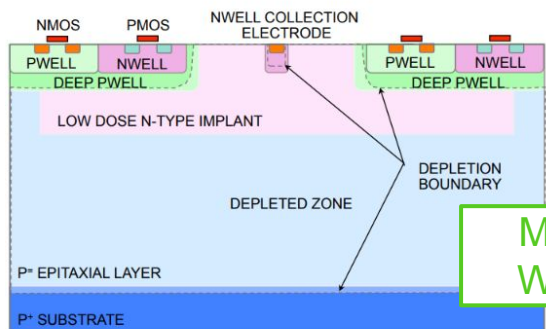
MODIFIED WITH GAP

selection of pixel architecture
 evaluation of detection efficiency
 evaluation of radiation hardness

CHARACTERIZATION GOALS FOR TECHNOLOGY VALIDATION



<https://doi.org/10.1016/j.nima.2017.07.046>



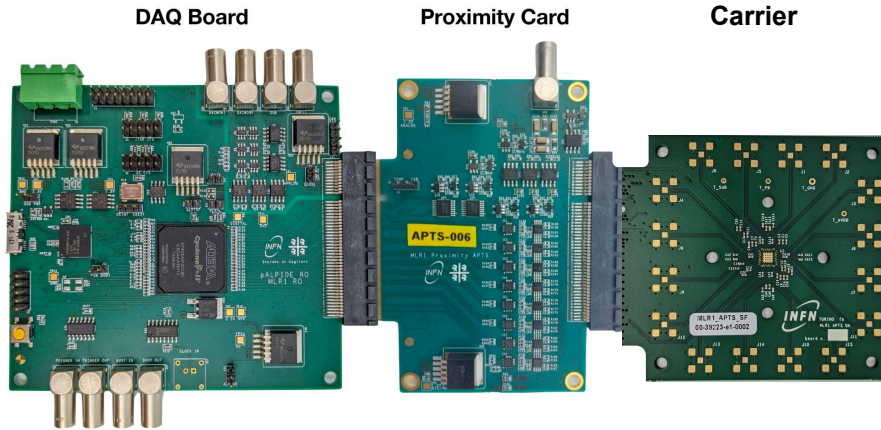
<http://dx.doi.org/10.1088/1748-0221/14/05/C05013>

ALICE ITS3: D-MAPS with small collection diode in 65 nm

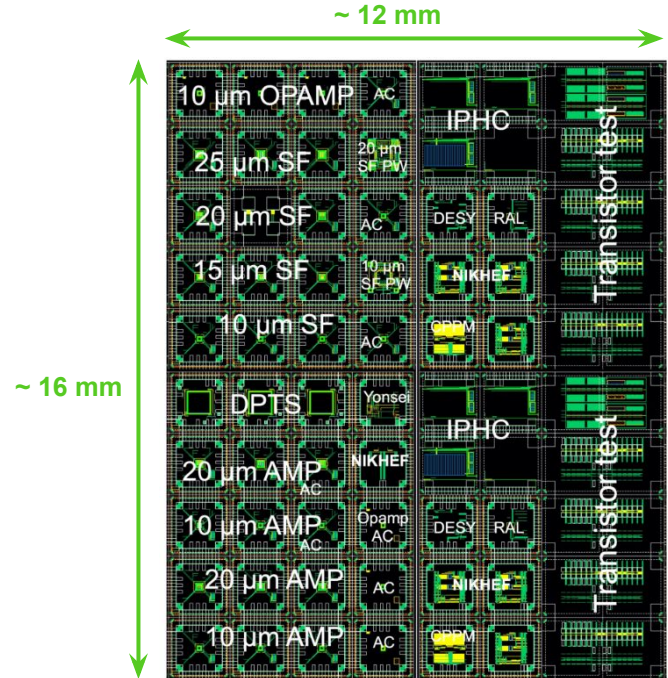
ALICE ITS3 involved in the evaluation of the TPSCo 65 nm technology performance for particle detection

Multi Layer Reticle “MLR1” submission:

- transistor test structures for radiation hardness studies
- various diode matrices for charge-collection studies
- analog building blocks



D-MAPS: depleted monolithic active pixel sensors



First sensor prototypes in 65 nm process in collaboration with CERN EP R&D on monolithic sensors

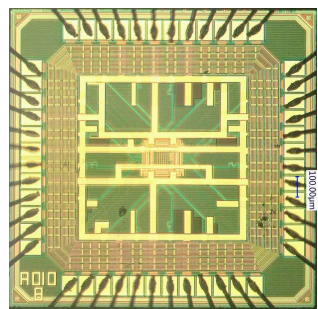
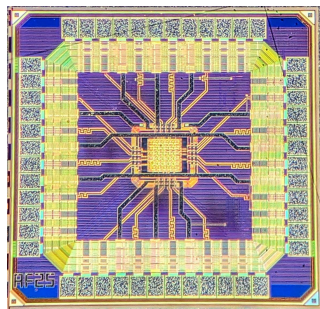
Test structures

APTS

Analogue Pixel Test Structure

Source-follower

OpAmp



1.5 mm

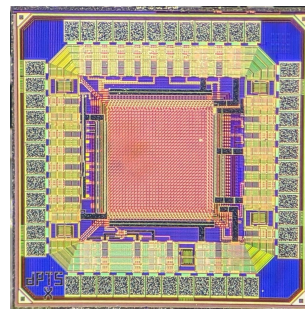
1.5 mm

1.5 mm

- Matrix: 6x6 pixels
- Pitch: 10, 15, 20, 25 μm
- Direct analogue readout of central 4x4 submatrix
- AC/DC coupling
- 3 process modifications
- Purpose: testing pixel cell

DPTS

Digital Pixel Test Structure



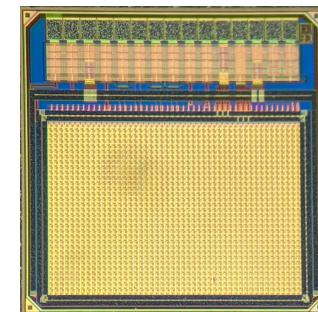
1.5 mm

1.5 mm

- Matrix: 32x32 pixels
- Pitch: 15 μm
- Asynchronous digital readout
- Time-over-Threshold information
- Only modified with gap process modification
- Purpose: testing pixel front-end

CE-65

Circuit Exploratoire 65



1.5 mm

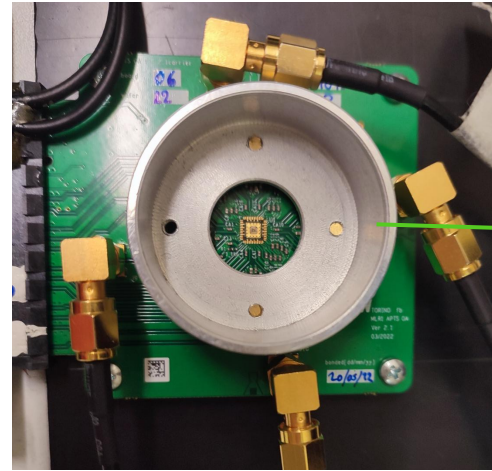
1.5 mm

- Matrix: 64x32, 48x32 pixels
- Pitch: 15, 25 μm
- Readout: rolling shutter analog
- Purpose: testing pixel with rolling shutter

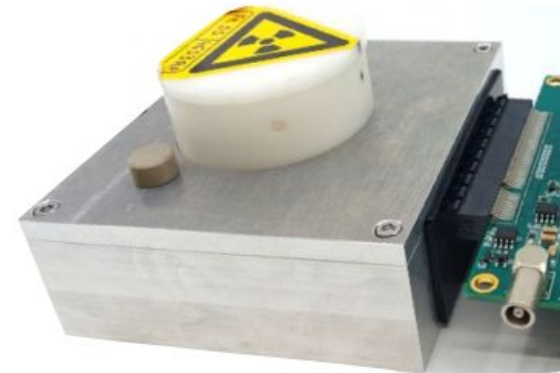
Characterization tests

Laboratory

1. Pulse and noise measurements
2. Tests with ^{55}Fe source (5.9 keV X-rays)
 - Tuning of chip parameters
 - Signal calibration
 - Study of the charge collection
 - Performance comparison of different process modification and split

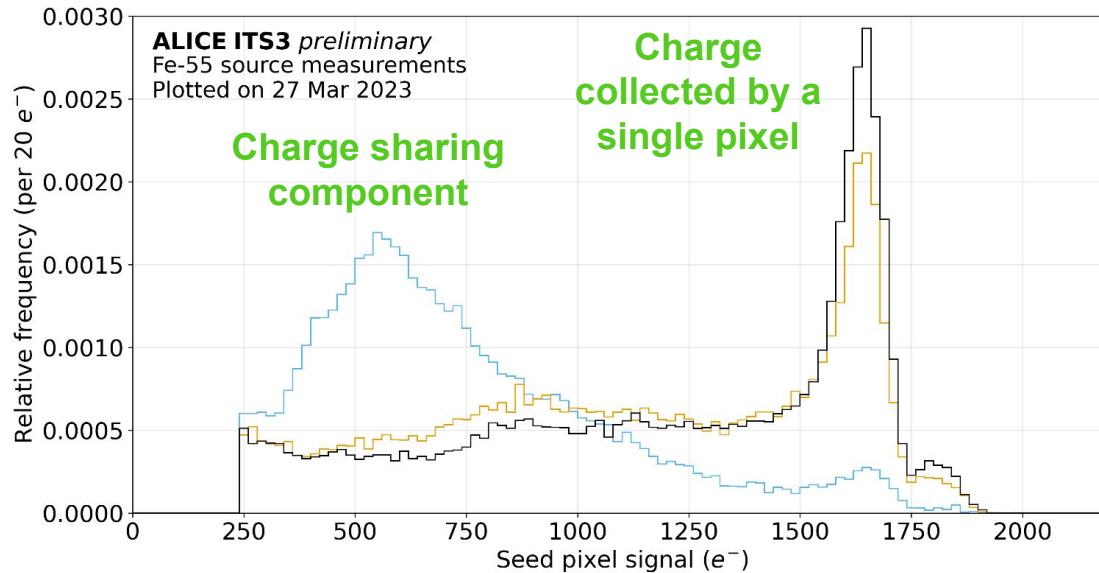
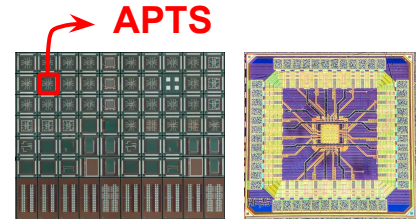


Aluminium holder



Impact of implant geometry

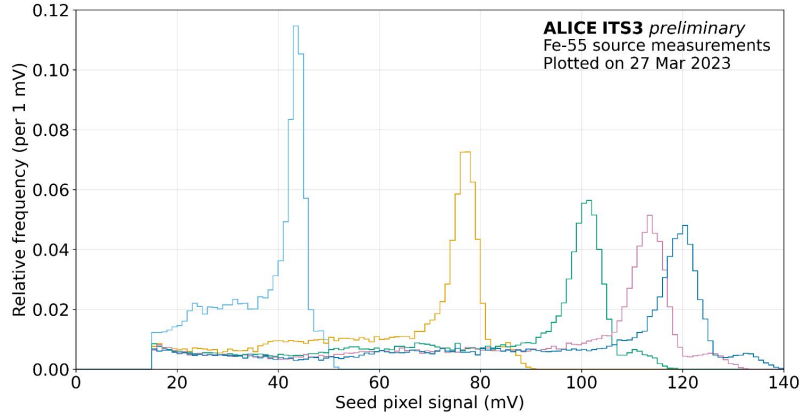
- Performance comparison of different prototype variants
- The standard process shows a charge sharing contribution that is not visible for the modified and modified with gap process



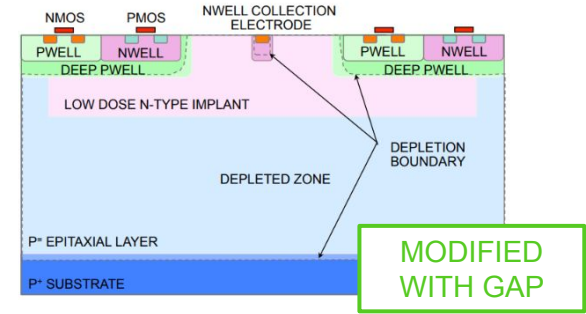
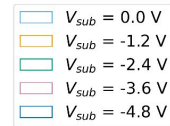
APTS SF
pitch: 15 μm
split: 4
 $I_{\text{reset}} = 100 \text{ pA}$
 $I_{\text{biasn}} = 5 \mu\text{A}$
 $I_{\text{biasp}} = 0.5 \mu\text{A}$
 $I_{\text{bias4}} = 150 \mu\text{A}$
 $I_{\text{bias3}} = 200 \mu\text{A}$
 $V_{\text{reset}} = 500 \text{ mV}$
 $V_{\text{sub}} = V_{\text{pwell}} = -1.2 \text{ V}$

Standard
Modified
Modified with gap

Reverse bias and pixel pitch influence

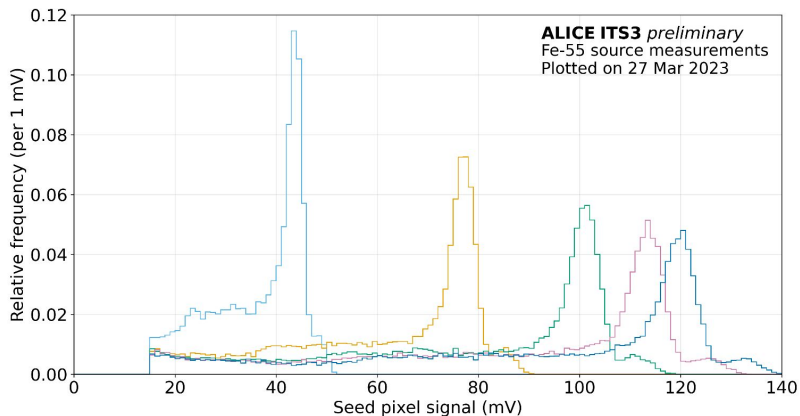


APTS SF
pitch: 15 μm
type: modified with gap
split: 4
 $I_{\text{reset}} = 100 \mu\text{A}$
 $I_{\text{bias1}} = 5 \mu\text{A}$
 $I_{\text{bias2}} = 0.5 \mu\text{A}$
 $I_{\text{bias3}} = 150 \mu\text{A}$
 $I_{\text{bias4}} = 200 \mu\text{A}$
 $V_{\text{reset}} = 500 \text{mV}$
 $V_{\text{sub}} = V_{\text{well}}$



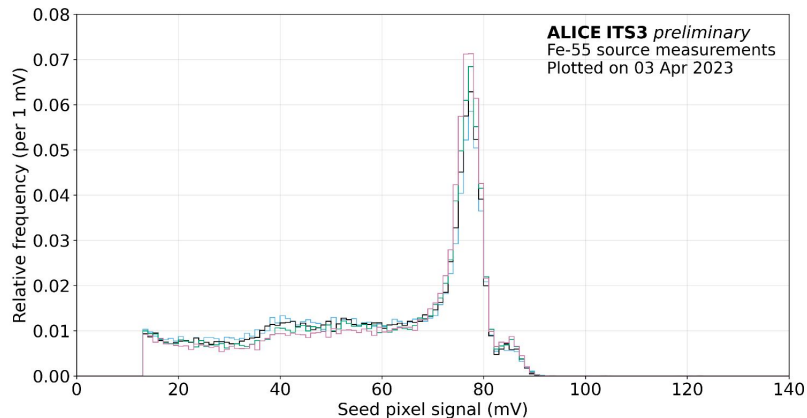
- Signal amplitude increases with reverse bias \rightarrow reduction of input node capacitance

Reverse bias and pixel pitch influence



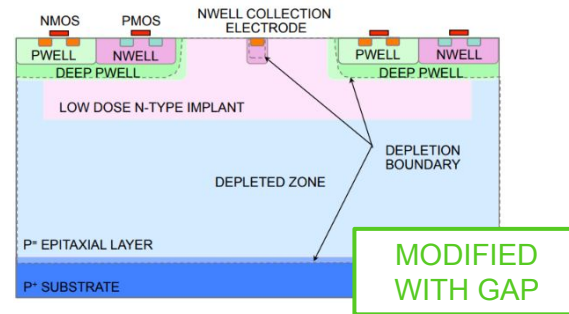
APTS SF
pitch: 15 μm
type: modified with gap
split: 4
 $I_{\text{reset}} = 100 \text{ pA}$
 $I_{\text{bias1}} = 5 \text{ }\mu\text{A}$
 $I_{\text{bias2}} = 0.5 \text{ }\mu\text{A}$
 $I_{\text{bias3}} = 150 \text{ }\mu\text{A}$
 $I_{\text{bias4}} = 200 \text{ }\mu\text{A}$
 $V_{\text{reset}} = 500 \text{ mV}$
 $V_{\text{sub}} = V_{\text{pwell}}$

— $V_{\text{sub}} = 0.0 \text{ V}$
— $V_{\text{sub}} = -1.2 \text{ V}$
— $V_{\text{sub}} = -2.4 \text{ V}$
— $V_{\text{sub}} = -3.6 \text{ V}$
— $V_{\text{sub}} = -4.8 \text{ V}$



APTS SF
type: modified with gap
split: 4
 $I_{\text{reset}} = 100 \text{ pA}$
 $I_{\text{bias1}} = 5 \text{ }\mu\text{A}$
 $I_{\text{bias2}} = 0.5 \text{ }\mu\text{A}$
 $I_{\text{bias3}} = 150 \text{ }\mu\text{A}$
 $I_{\text{bias4}} = 200 \text{ }\mu\text{A}$
 $V_{\text{reset}} = 500 \text{ mV}$
 $V_{\text{sub}} = V_{\text{pwell}} = -1.2 \text{ V}$


— Pitch = 10 μm
— Pitch = 15 μm
— Pitch = 20 μm
— Pitch = 25 μm



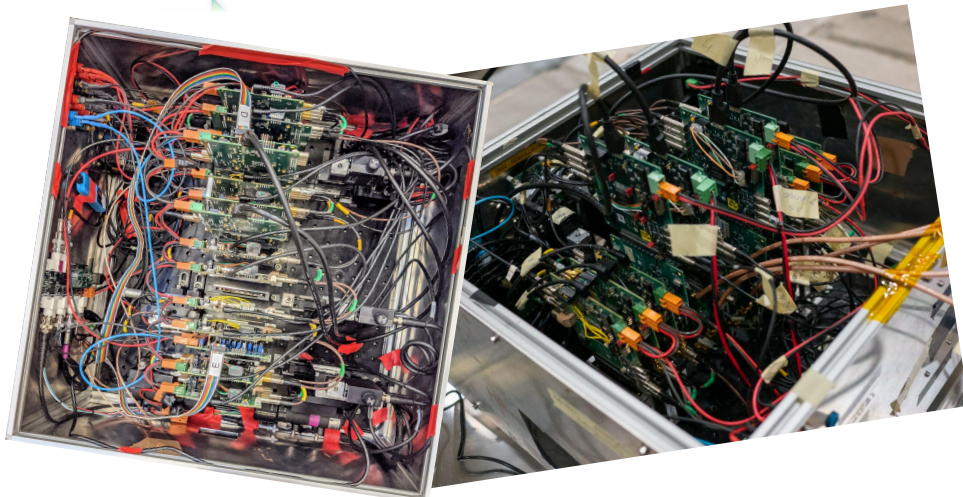
- Signal amplitude increases with reverse bias \rightarrow reduction of input node capacitance
- Modified with gap shows the best performance in terms of charge collected by one pixel \rightarrow independent from pixel pitch

Characterization tests

In-beam measurements:

- Use of charged particles (π , e^-)
- Reconstruction of particles tracks using the Corryvreckan framework 
- Association of tracks with cluster on the plane

 **Efficiency and FHR**
Spatial and temporal resolution



Beam test campaigns completed:

2021

DESY September 2021 - DPTS
PS October 2021 - APTS-DPTS
SPS November 2021 - APTS-DPTS
DESY December 2021 - DPTS

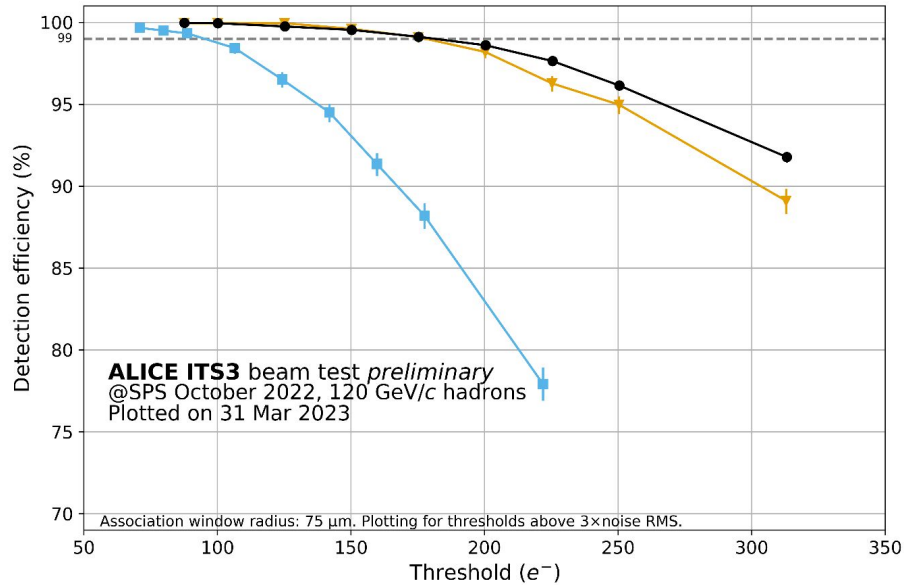
2022

DESY March 2022 - DPTS
MAMI April 2022 - APTS SF
PS May 2022 - DPTS
PS June 2022 - APTS SF
SPS June 2022 - APTS OA
PS July 2022 - DPTS
PS August 2022 - APTS
SPS October 2022 - APTS
SPS November 2022 - DPTS
SPS November 2022 - APTS OA
DESY December 2022 - DPTS

2023

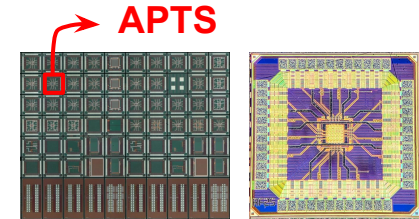
PS May 2023 - APTS SF and DPTS
SPS May 2023 - APTS SF
SPS June 2023 - APTS OPAMP
SPS July 2023 - APTS-SF

Process impact on APTS detection efficiency



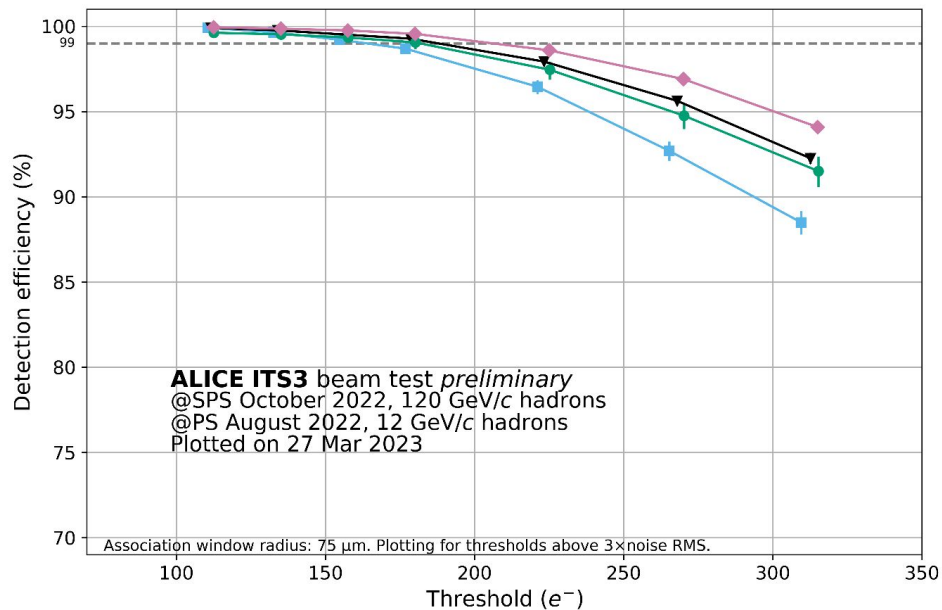
APTS SF
 Non-irradiated
 pitch: 15 μm
 split: 4
 $I_{\text{reset}} = 100 \text{ pA}$
 $I_{\text{bias1}} = 5 \text{ }\mu\text{A}$
 $I_{\text{bias2}} = 0.5 \text{ }\mu\text{A}$
 $I_{\text{bias3}} = 150 \text{ }\mu\text{A}$
 $I_{\text{bias4}} = 200 \text{ }\mu\text{A}$
 $V_{\text{reset}} = 500 \text{ mV}$
 $V_{\text{pwell}} = V_{\text{sub}} = -1.2 \text{ V}$
 $T = 20 \text{ }^\circ\text{C}$

- Standard
- Modified
- Modified with gap



More than 99% detection efficiency over large threshold range for modified processes

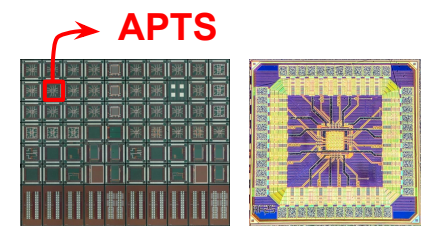
Pixel pitch influence on APTS detection efficiency



ALICE ITS3 beam test *preliminary*
@SPS October 2022, 120 GeV/c hadrons
@PS August 2022, 12 GeV/c hadrons
Plotted on 27 Mar 2023

APTS SF
Non-irradiated
type: modified with gap
split: 4
 $I_{reset} = 100 \text{ pA}$
 $I_{biasn} = 5 \text{ }\mu\text{A}$
 $I_{biasp} = 0.5 \text{ }\mu\text{A}$
 $I_{bias4} = 150 \text{ }\mu\text{A}$
 $I_{bias3} = 200 \text{ }\mu\text{A}$
 $V_{reset} = 500 \text{ mV}$
 $V_{pwell} = V_{sub} = 0 \text{ V}$
 $T = 20 \text{ }^\circ\text{C}$

- Pitch = 10 μm
- Pitch = 15 μm
- Pitch = 20 μm
- Pitch = 25 μm



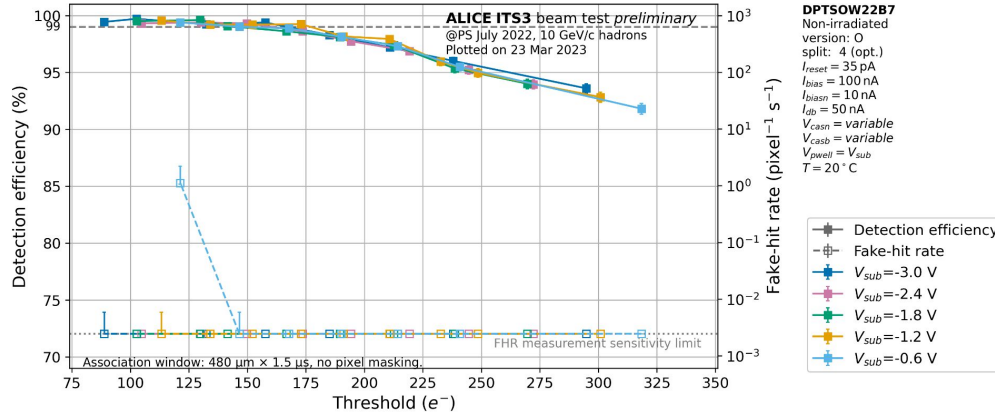
Different pitches:
different ratios of border
and central pixel regions

➡ larger pixels have
less border contribution

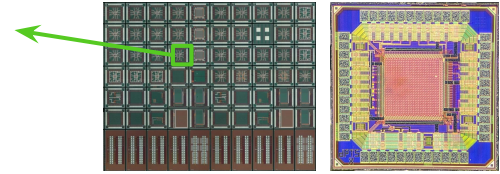
➡ less events with
charge sharing

Detection efficiency increases with pixel pitch in the modified with gap process

Reverse bias influence on detection efficiency and FHR

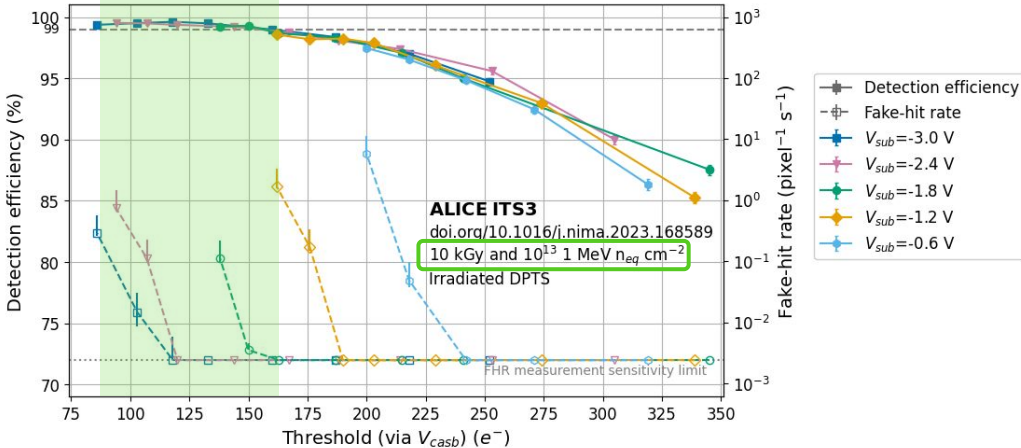
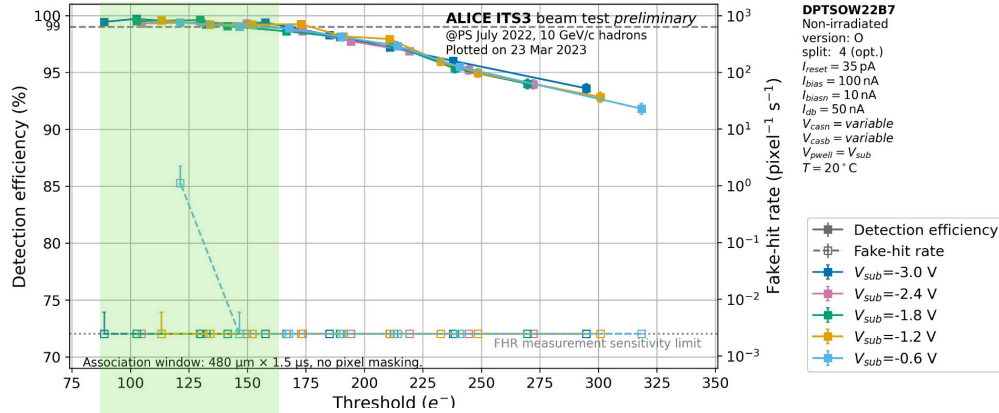


DPTS

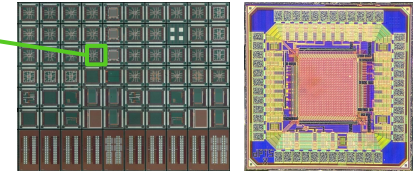


wide operational range of the sensor featuring a detection efficiency above 99%

Reverse bias influence on detection efficiency and FHR



DPTS



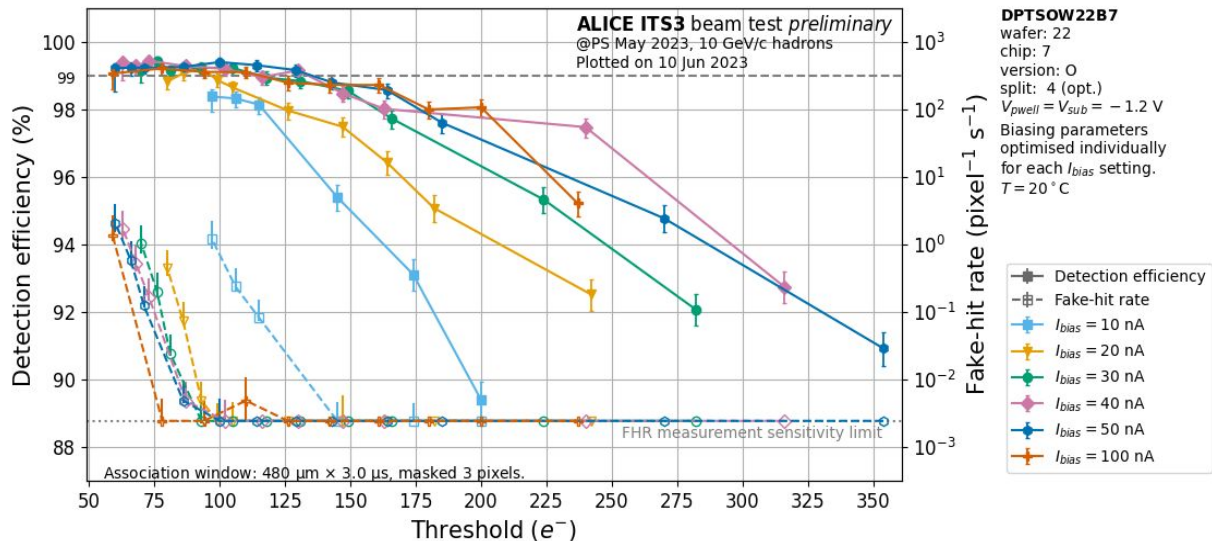
wide operational range of the sensor featuring a detection efficiency above 99%



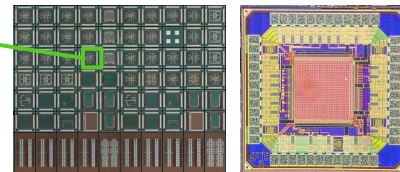
After irradiation
10 kGy + $10^{13} \text{ 1 MeV neq/cm}^2$
 (ALICE ITS3 requirement)

larger reverse bias voltages are favourable to operate the sensor at lower threshold values

I_{bias} influence on detection efficiency and FHR



DPTS



DPTSOW22B7
 wafer: 22
 chip: 7
 version: O
 split: 4 (opt.)
 $V_{pwell} = V_{sub} = -1.2 \text{ V}$
 Biasing parameters
 optimised individually
 for each I_{bias} setting.
 $T = 20^\circ \text{C}$

$I_{bias} = 10 \text{ nA}$

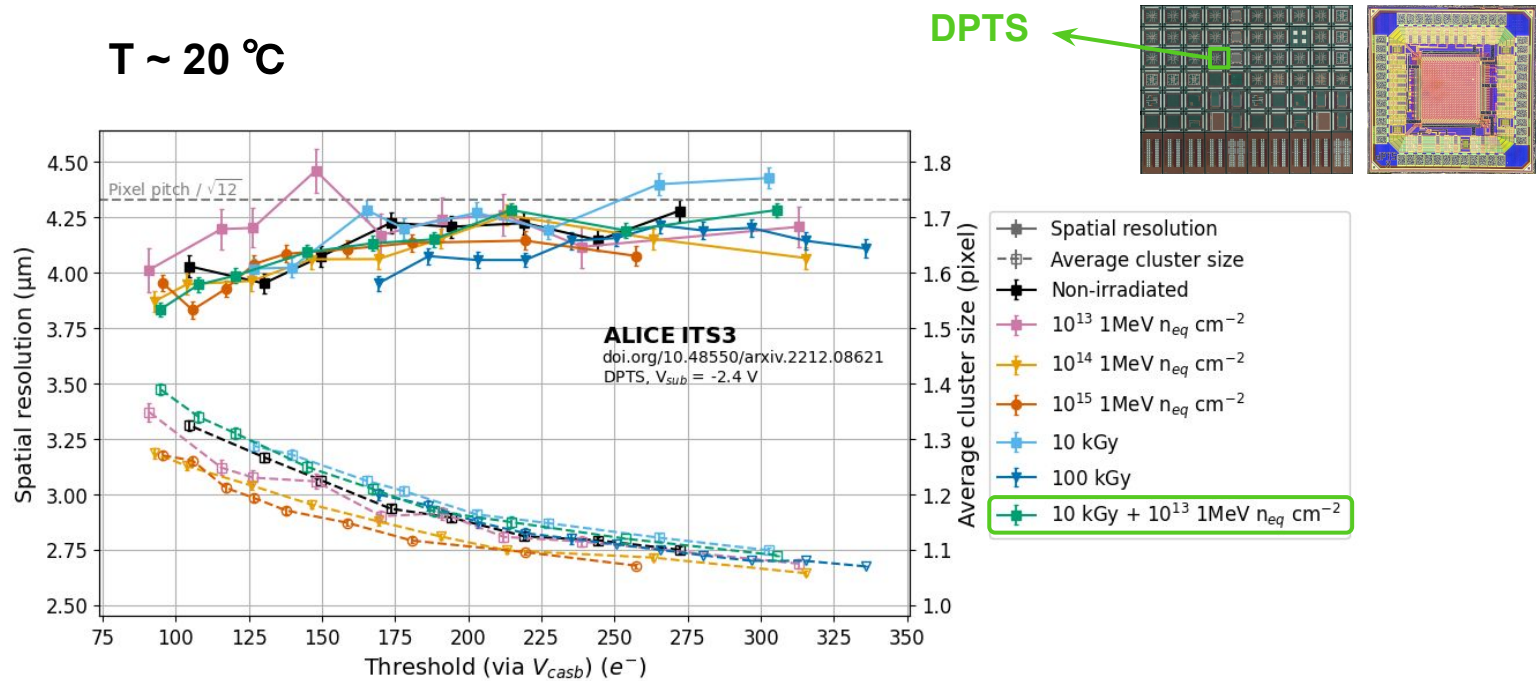
→ power consumption $\sim 5 \text{ mW cm}^{-2}$

$I_{bias} = 30 \text{ nA}$

→ power consumption $\sim 15 \text{ mW cm}^{-2}$

below the target!

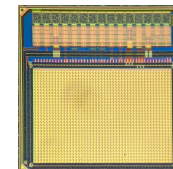
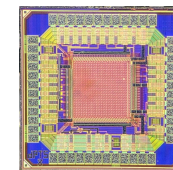
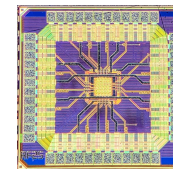
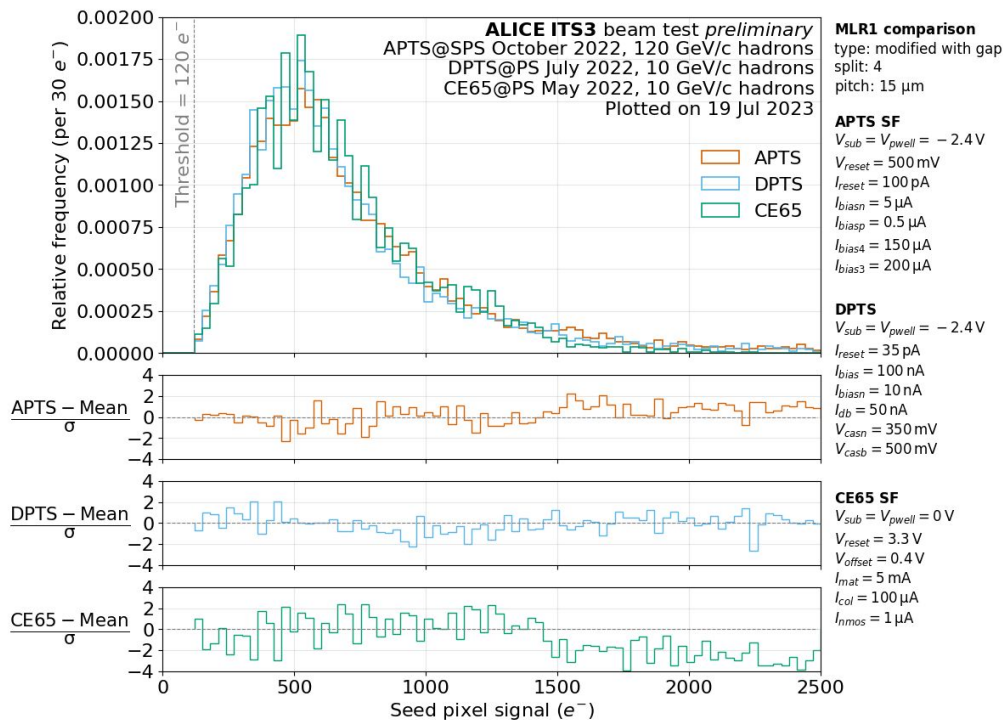
Effect of irradiation level on spatial resolution and cluster size



- Different levels of irradiation for various TID and NIEL
- Spatial resolution comparable for different irradiation levels
- Cluster size slightly decreases with NIEL irradiation

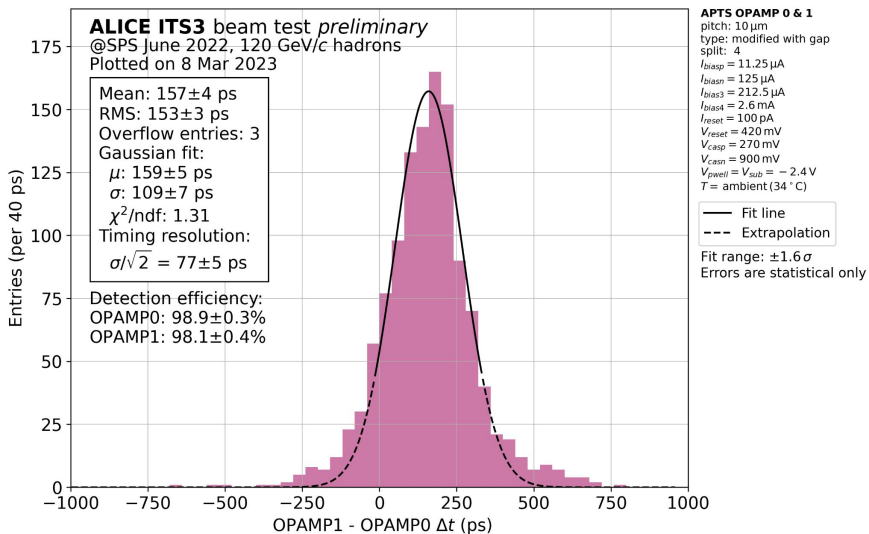
APTS vs DPTS vs CE65 testbeam comparison

Seed pixel signal normalized spectra in electrons are all in agreement



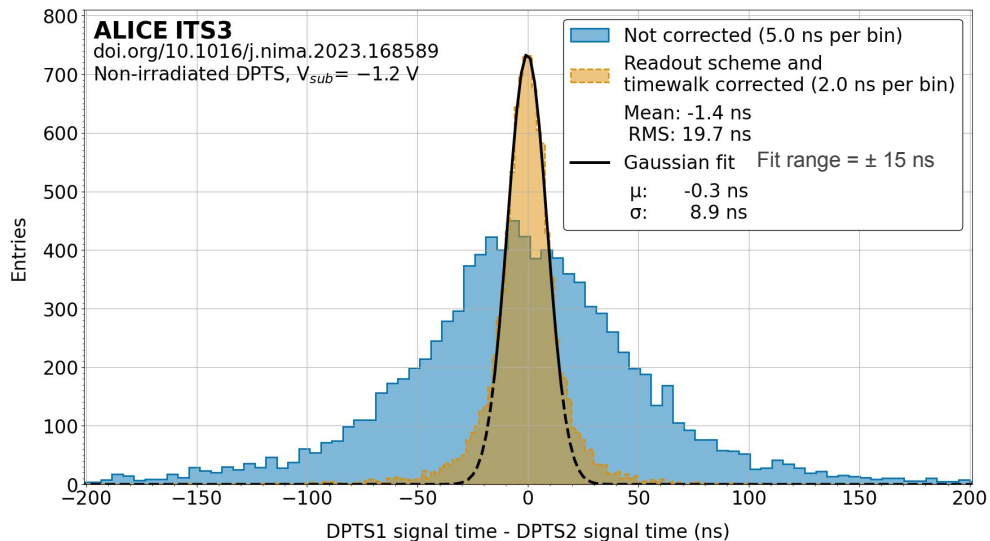
Timing resolution

APTS-OpAmp



Sensor contribution only
~ 77 ps

DPTS



- Readout scheme correction: correction for a fixed offset introduced for odd and even columns
- Time walk correction: fit the ToA vs ToT distribution and subtraction of the value from the measured data points

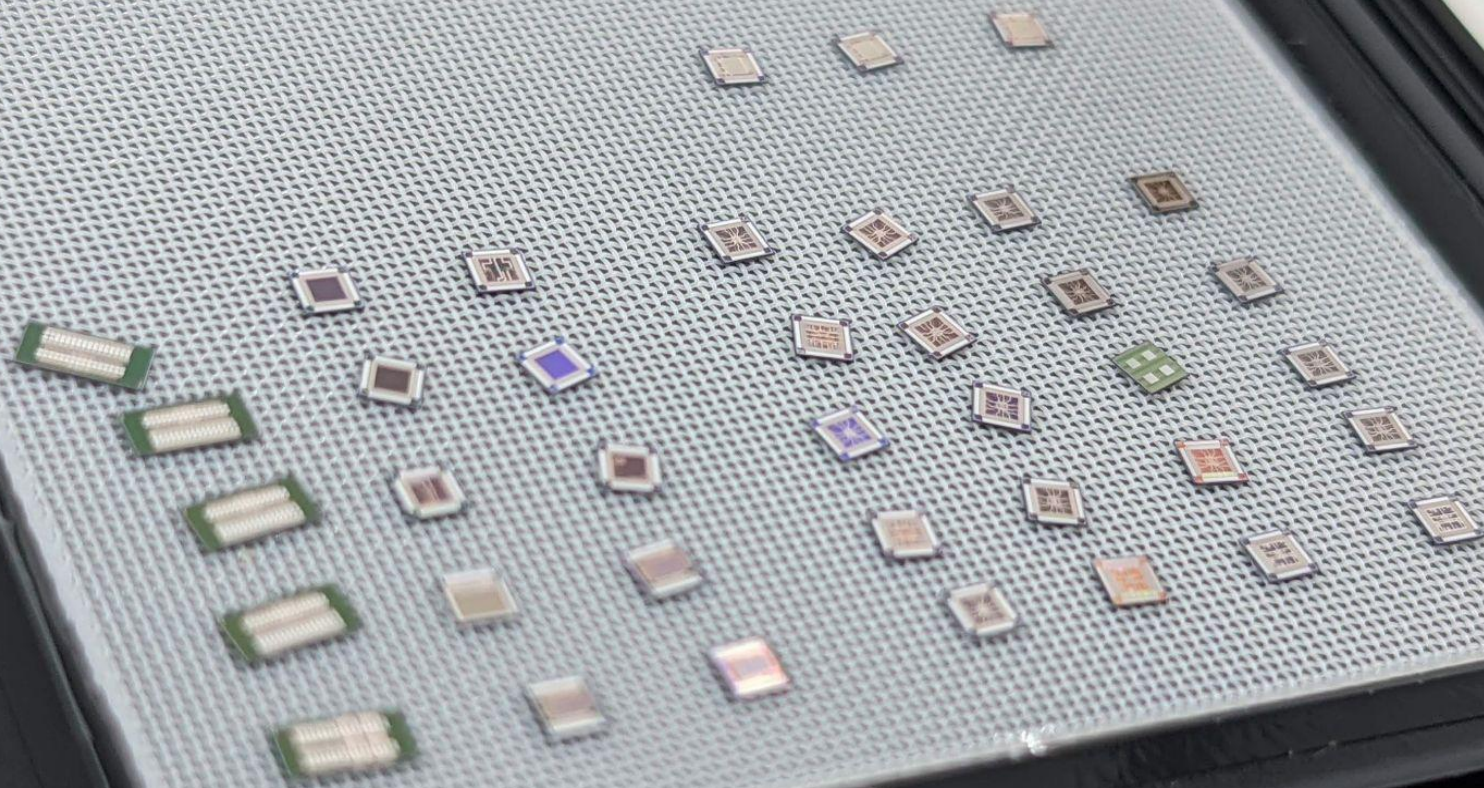
Sensor + front-end
~ 6 ns

Summary

- Extensive test campaigns have been carried out with ^{55}Fe source on different APTS prototypes:
 - modified with gap process showed the best charge collection performance with suppression of charge sharing
- Multiple beam tests:
 - Above 99% detection efficiency for a wide range of working points
 - Radiation hardness better than the requirement from ALICE ITS3 ($10\text{ kGy} + 10^{13}\text{ 1MeV neq/cm}^2$)
 - Spatial resolution and cluster size measured for different irradiation levels up to $10^{15}\text{ 1MeV neq/cm}^2$ and 100 kGy
 - Timing resolution measured for both APTS OpAmp ($\sim 77\text{ ps}$) and DPTS ($\sim 6\text{ ns}$)

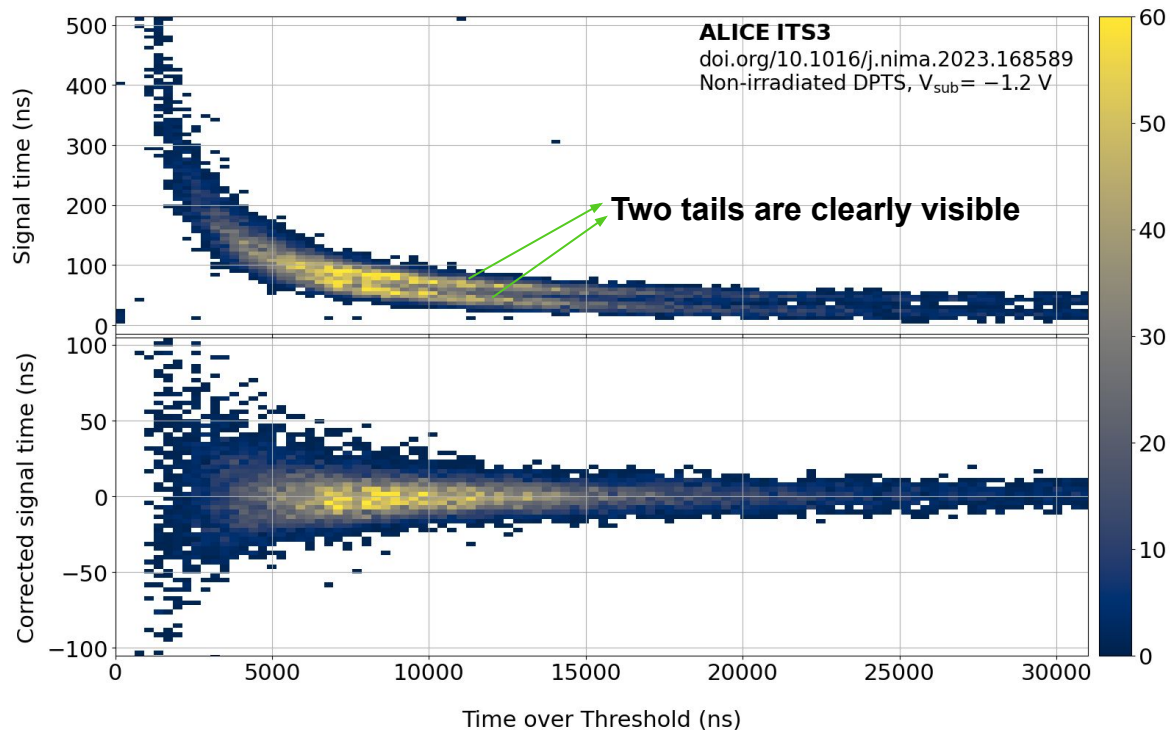
The 65 nm technology has been validated for particle detection in terms of charge collection efficiency, detection efficiency and radiation hardness

Thank you for the attention!



Backup slides

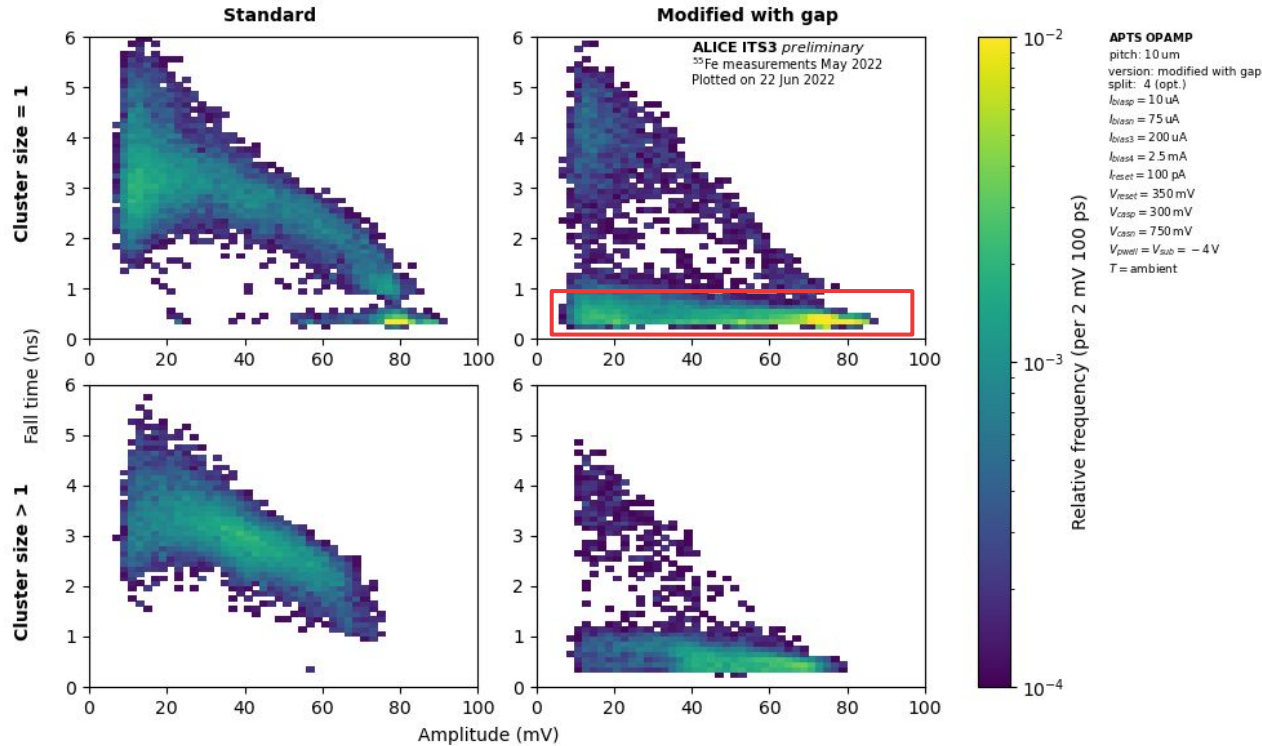
DPTS ToA vs ToT distribution



1. **Correction for readout scheme:** subtraction of the asymptotic value of the two tails from even and odd columns

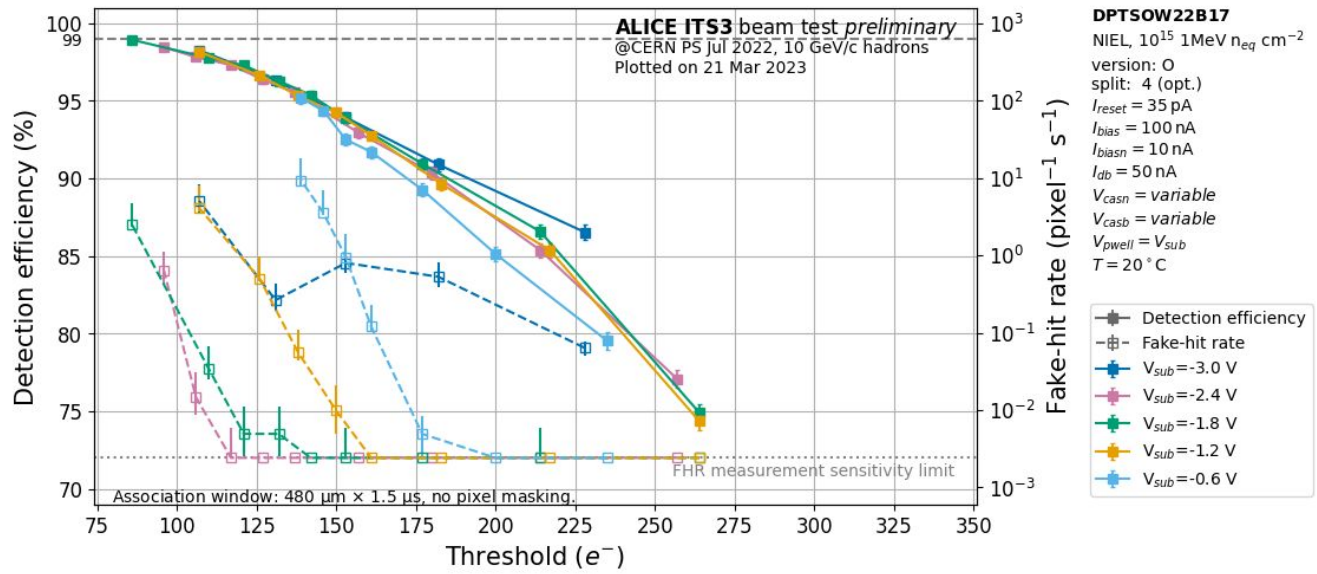
2. **Correction for time walk:** fit the data with
$$\text{Signal time} = A + \frac{B}{ToT - C}$$
and subtraction of its value from the measured data

APTS OpAmp - Fall time vs amplitude

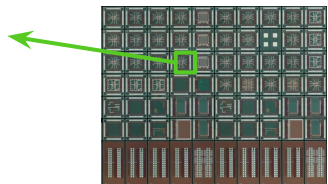


Modified with gap: 80% of cluster size 1 events lies in the region with fall time lower than 1 ns, compared with 20% of the standard process

Reverse bias influence - NIEL 10^{15} 1MeV neq/cm²

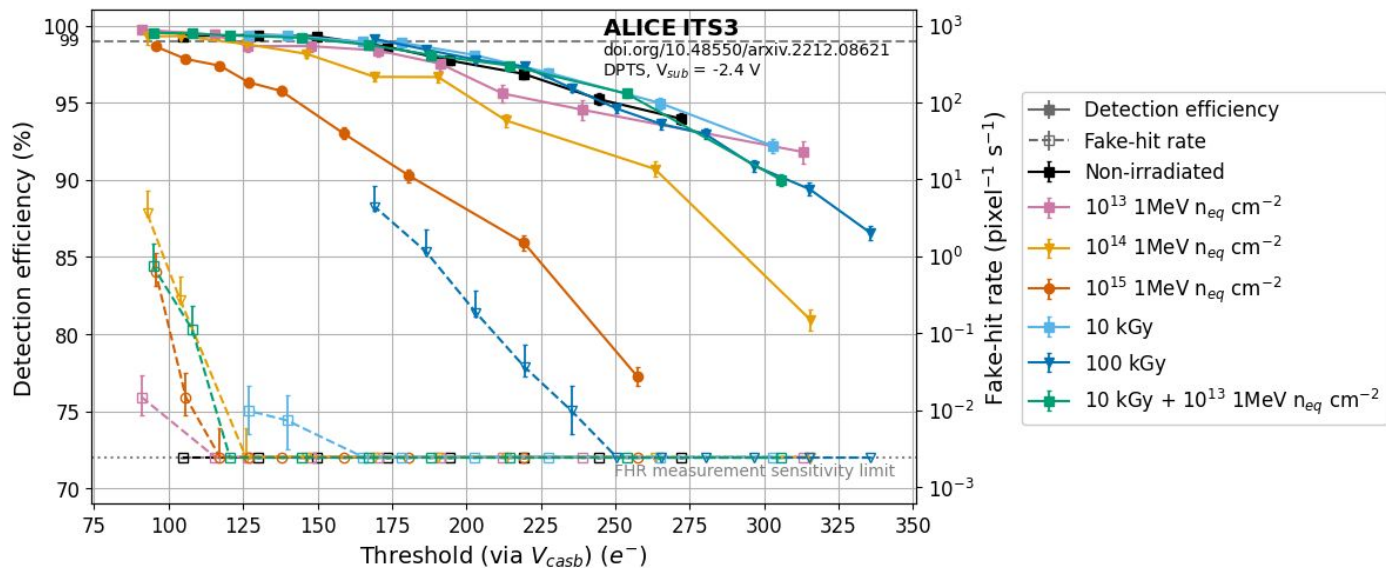


DPTS



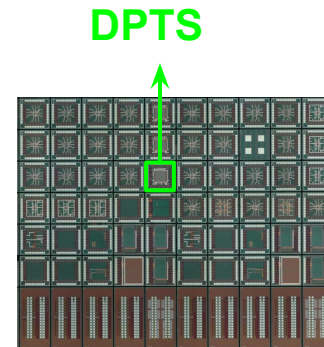
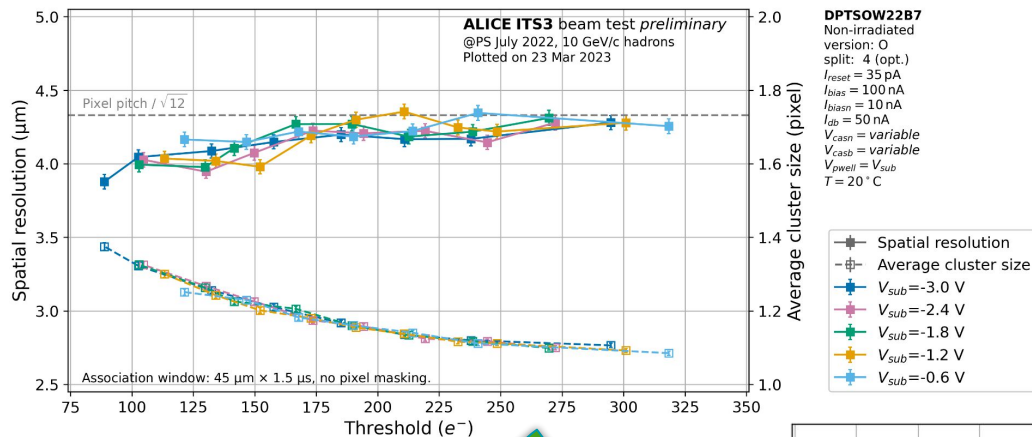
~ 99% efficiency reached at 20°C

Irradiation level impact on Efficiency and FHR

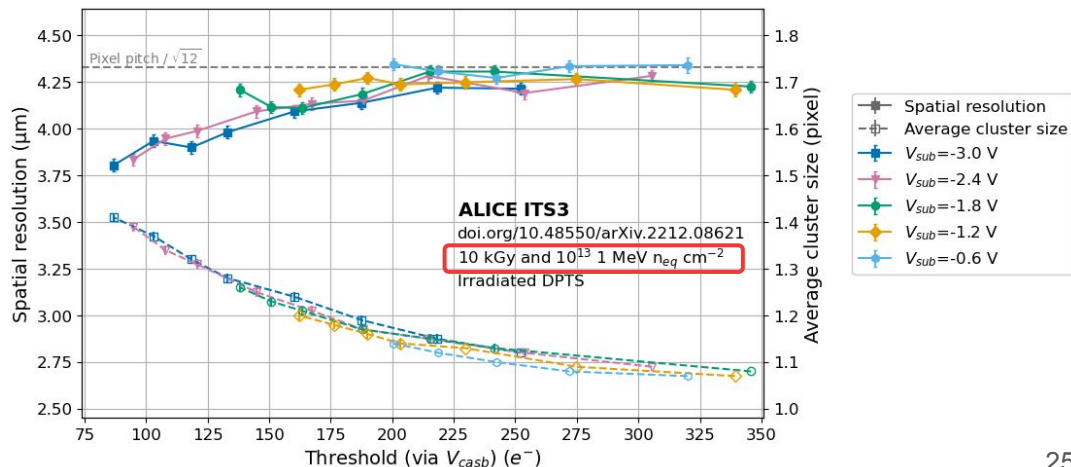
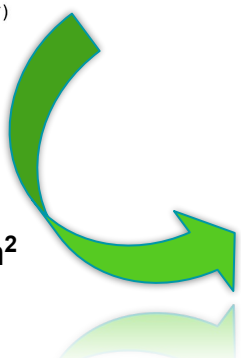


Only the 10^{15} 1MeV neq/cm^2 irradiated sensor shows performance deterioration

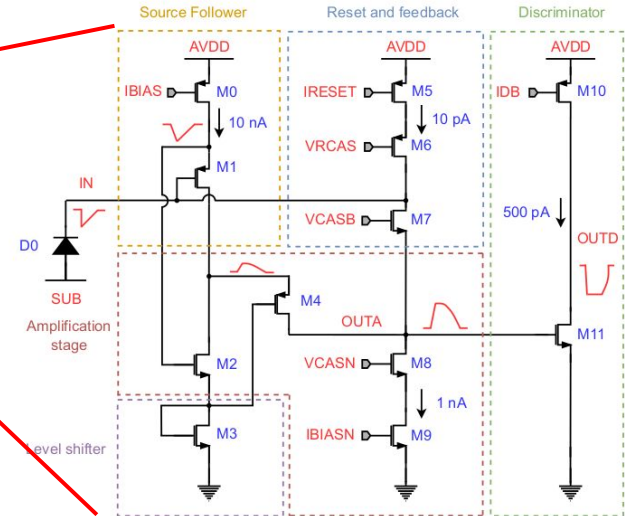
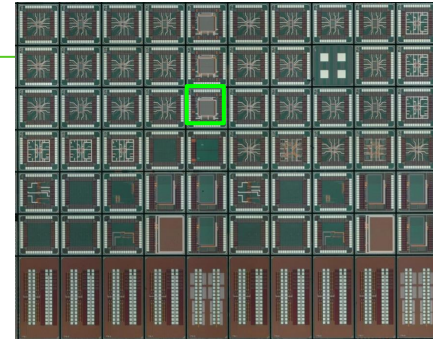
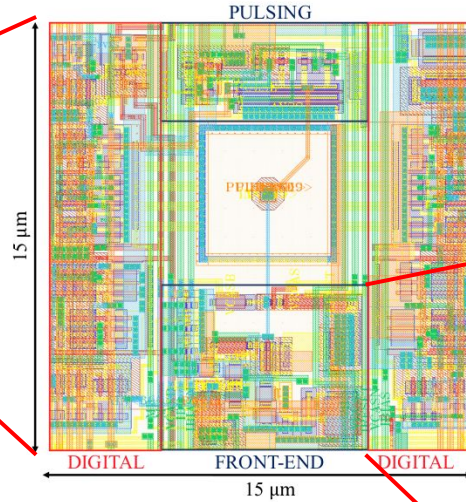
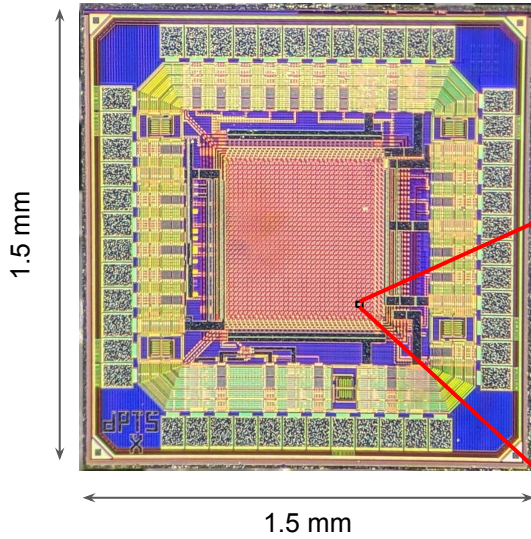
Reverse bias influence on DPTS spatial resolution and cluster size



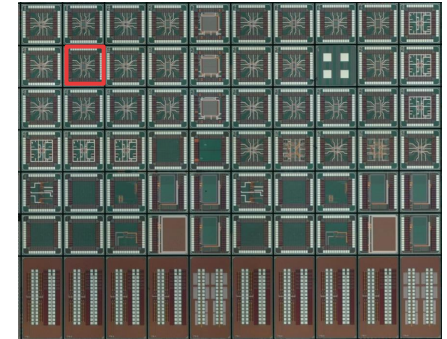
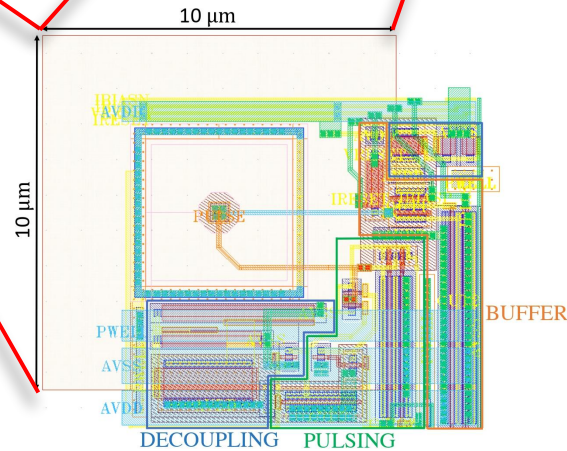
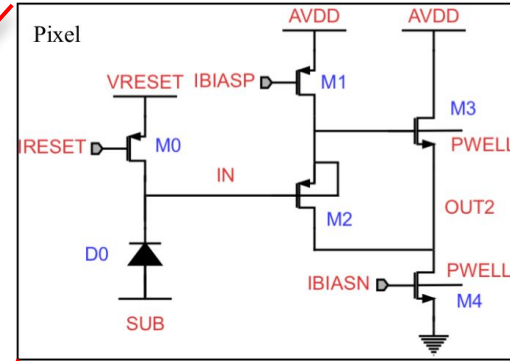
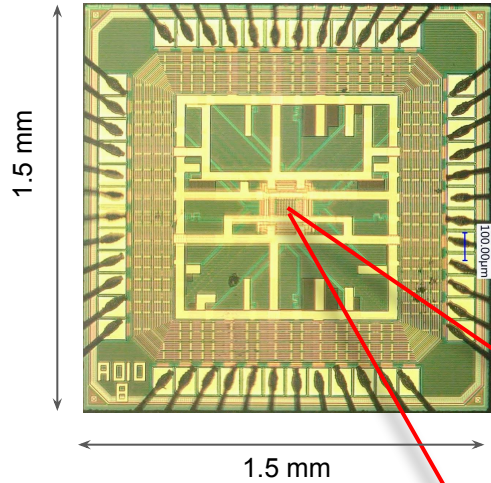
After irradiation
10 kGy + 10^{13} 1MeV neq/cm²
(ALICE ITS3 requirement)



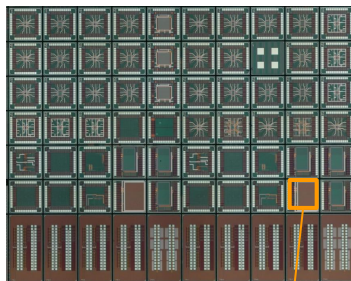
Monolithic design - DPTS



Monolithic design - APTS



CE65: Process modification reduces charge sharing



CE65

- In-pixel architecture and process have an impact on the charge collection properties
- Effect observed in APTS with ^{55}Fe sources confirmed at beam test
- In modified process all charge is mostly collected by single pixel

